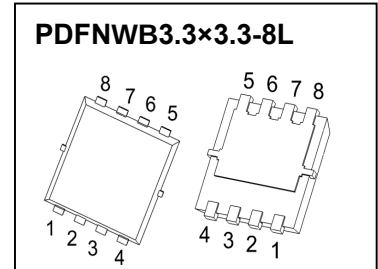




PDFNWB3.3×3.3-8L Plastic-Encapsulate MOSFETS

CJAB35N03 N-Channel Power MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
30 V	7mΩ@10V	35A
	12mΩ@4.5V	



DESCRIPTION

The CJAB35N03 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications

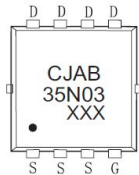
FEATURES

- High density cell design for ultra low $R_{DS(ON)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

APPLICATIONS

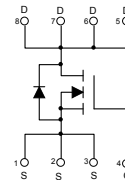
- High side switch in POL DC/DC converter
- Secondary side synchronous rectifier

MARKING



CJAB35N03 = Part No.
Solid dot=Pin1 indicator
XXX=Date Code

EQUIVALENT CIRCUIT



MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D^{(1)}$	35	A
Pulsed Drain Current	I_{DM}	120	A
Single Pulsed Avalanche Energy	$E_{AS}^{(2)}$	150	mJ
Power Dissipation	P_D	1.5	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}^{(1)}$	83.3	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 ~+150	$^\circ\text{C}$
Lead Temperature for Soldering Purposes(1/8" from case for 10s)	T_L	260	$^\circ\text{C}$

(1).Mounted on a glass epoxy board of 25.4 mm x 25.4 mm x 0.8 mmt

(2). E_{AS} condition: $V_{DD}=15\text{V}$, $L=0.1\text{mH}$, $R_G=25\Omega$, Starting $T_J = 25^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS

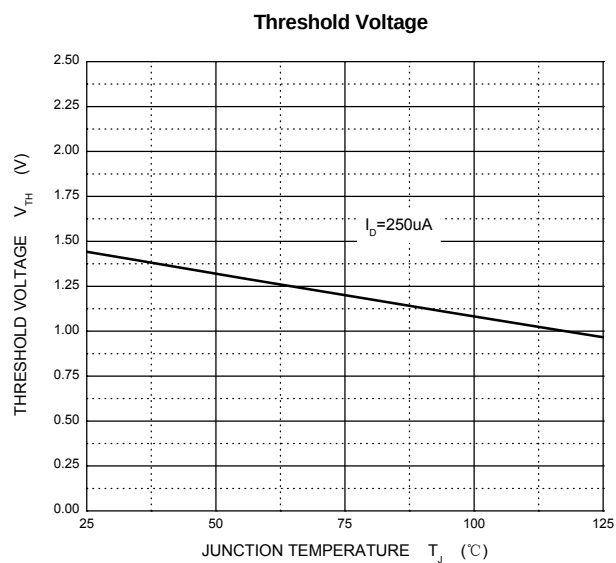
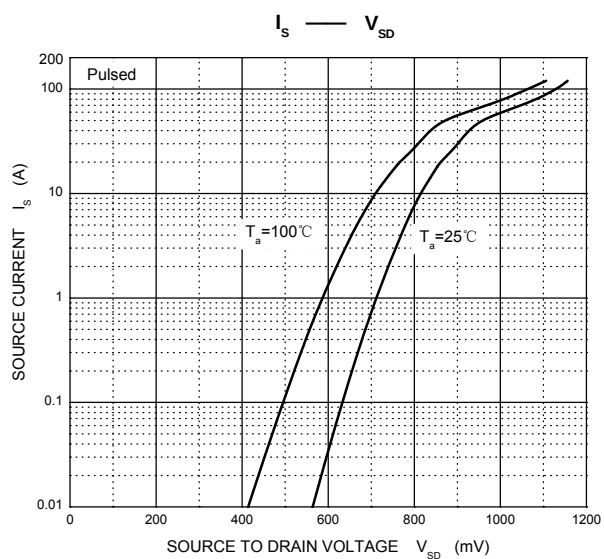
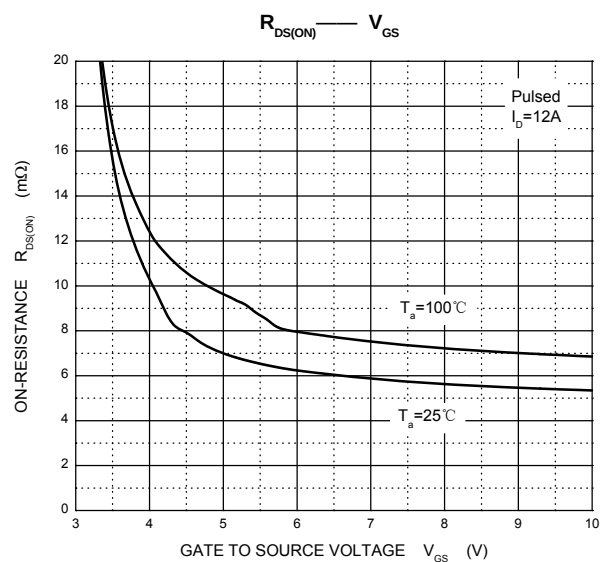
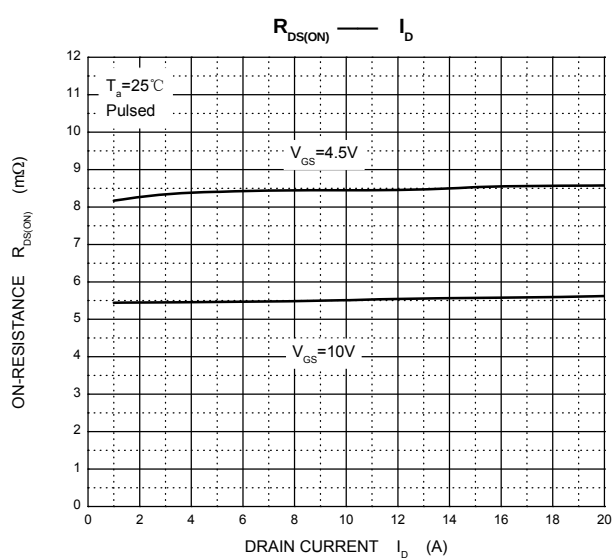
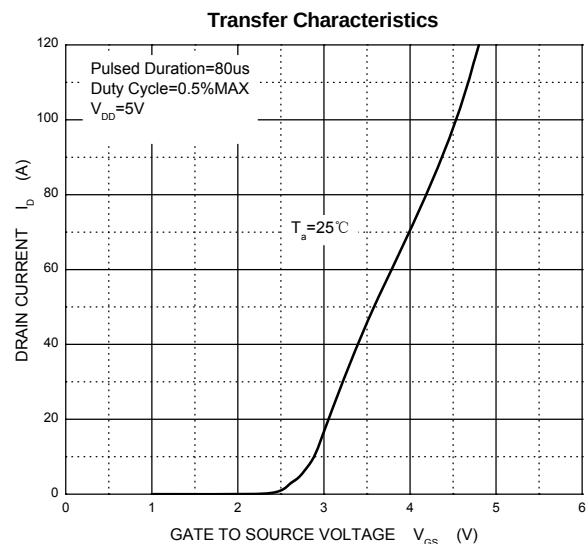
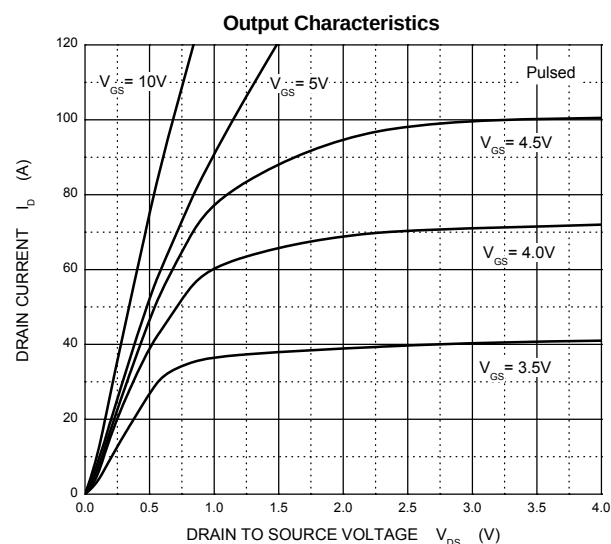
$T_a=25^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Off characteristics						
Drain-source breakdown voltage	V _{(BR) DSS}	V _{GS} = 0V, I _D =250μA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1	μA
Gate-body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
On characteristics (note1)						
Gate-threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	3.0	V
Static drain-source on-sate resistance	R _{DS(on)}	V _{GS} =4.5V, I _D =10A		8.2	12	mΩ
		V _{GS} =10V, I _D =12A		5.5	7.0	mΩ
Forward transconductance	g _{FS}	V _{DS} =10V, I _D =12A	30			S
Dynamic characteristics (note 2)						
Input capacitance	C _{iss}	V _{DS} =15V,V _{GS} =0V, f =1MHz		1265		pF
Output capacitance	C _{oss}			600		
Reverse transfer capacitance	C _{rss}			130		
Switching characteristics (note 2)						
Total gate charge	Q _g	V _{DS} =15V, V _{GS} =10V, I _D =12A		19		nC
Gate-source charge	Q _{gs}			2.7		
Gate-drain charge	Q _{gd}			2.5		
Turn-on delay time	t _{d(on)}	V _{DD} =15V,I _D =12A, V _{GS} =10V,R _G =6Ω		18		ns
Turn-on rise time	t _r			10		
Turn-off delay time	t _{d(off)}			34		
Turn-off fall time	t _f			10		
Drain-Source Diode Characteristics						
Drain-source diode forward voltage(note1)	V _{SD}	V _{GS} =0V, I _S =12A		0.85	1.2	V
Continuous drain-source diode forward current(note3)	I _S				35	A
Pulsed drain-source diode forward current	I _{SM}				120	A

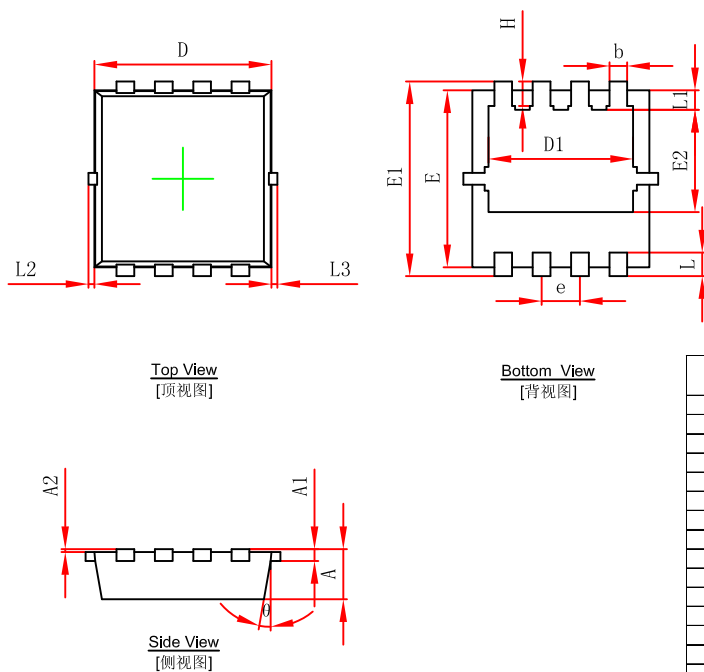
Notes:

1. Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
2. Guaranteed by design, not subject to production.
3. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Typical Characteristics

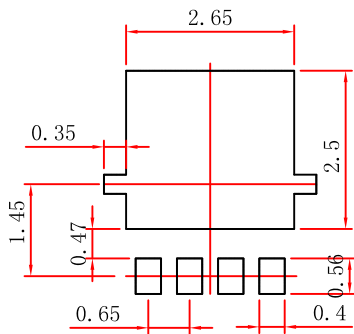


PDFNWB3.3x3.3-8L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°

PDFNWB3.3x3.3-8L Suggested Pad Layout

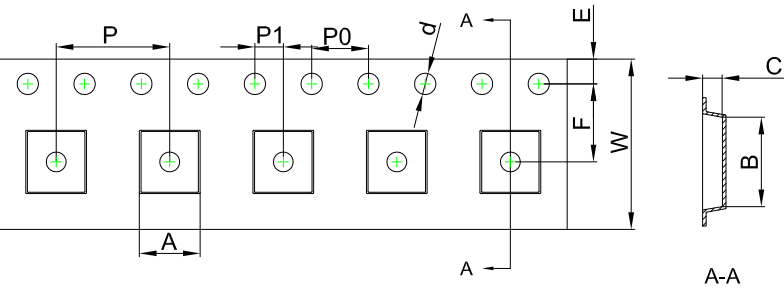


Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

NOTICE

JCET reserve the right to make modifications,enhancements, improvements, corrections or other changes without further notice to any product herein.JCET does not assume any liability arising out of the application or use of any product described herein.

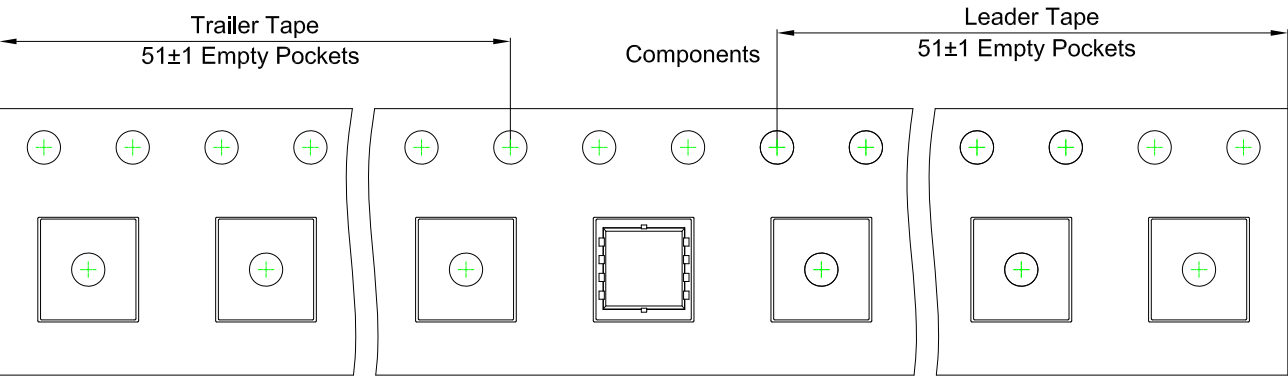
PDFNWB3.3×3.3-8L Embossed Carrier Tape



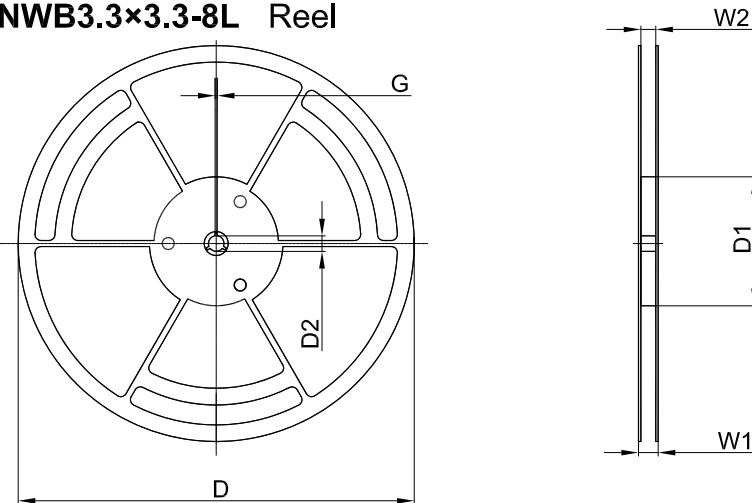
Packaging Description:
PDFNWB3.3×3.3-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 5,000 units per 13" or 33.0 cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

Dimensions are in millimeter										
Pkg type	A	B	C	d	E	F	P0	P	P1	W
PDFNWB3.3×3.3-8L	3.55	3.55	1.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

PDFNWB3.3×3.3-8L Tape Leader and Trailer



PDFNWB3.3×3.3-8L Reel



Dimensions are in millimeter						
Reel Option	D	D1	D2	G	W1	W2
13"Dia	Ø330.00	100.00	13.00	1.90	17.60	12.40

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)
5,000 pcs	13 inch	5,000 pcs	340×336×29	50,000 pcs	353×346×365